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(71) Applicant *(for all designated States except US)*: **FICO B.V.** [NL/NL]; Ratio 6, NL-6921 RW Duiven (NL).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **GAL, Wilhelmus, Gerardus, Jozef** [NL/NL]; Beekseweg 2, NL-7031 AX Kilder (NL). **DE VRIES, Franciscus, Bernardus, Antonius** [NL/NL]; Hasselt 11, NL-7152 KV Eibergen (NL).

(74) Agent: **VAN DEN HEUVEL, Henricus, Theodorus**; Patentwerk B.V., P.O. Box 1514, NL-5200 BN 's-Hertogenbosch (NL).

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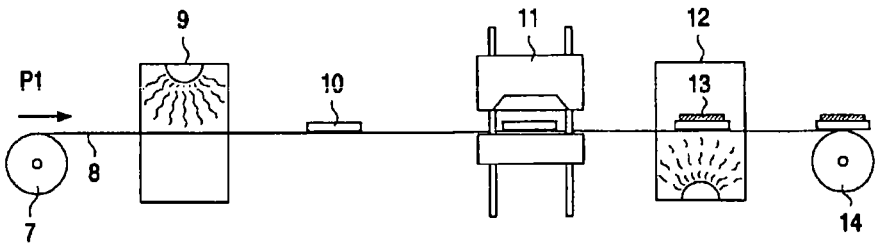
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(54) Title: METHOD FOR ENCAPSULATING AN ELECTRONIC COMPONENT USING A FOIL LAYER



(57) Abstract: The invention relates to a method for encapsulating an electronic component, in particular a semiconductor, fixed on a carrier, comprising the processing steps of: a) placing at least one foil layer in a mould, b) placing the carrier in contact with the foil layer with the side remote from the component, and c) encapsulating the electronic component with encapsulating material, characterized in that the foil layer undergoes a treatment whereby the adhesion of the foil layer is increased such that it adheres to the carrier. The invention also relates to a foil material for applying during such a method.

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